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Revision: E

**LITE-ON DCC** 

**RELEASE** 

BNS-OD-FC001/A4

### LITE-ON Technology Corp. / Optoelectronics

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### 1. **DESCRIPTION**

#### 1.1 Features

- Current transfer ratio ( CTR : MIN. 50% at  $I_F = 5mA$ ,  $V_{CE} = 5V$  )
- High input-output isolation voltage ( Viso = 5,000Vrms )
- High collector-emitter voltage ( V<sub>CEO</sub> = 70V )
- Temperature range -55°C to 110°C
- Creepage distance > 8mm
- Employs double transfer mold technology
- Long Mini-flat package: 2.3mm profile: LTV-10XX series
- Safety approval

UL 1577

Cul CA5A

VDE DIN EN60747-5-5 (VDE 0884-5)

CQC GB4943.1-2011/ GB8898-2011 (meet Altitude up to 5000m)

Nordic Safety (FIMKO/NEMKO/SEMKO/DEMKO)

■ RoHS Compliance

All materials be used in device are followed EU RoHS directive (No.2002/95/EC).

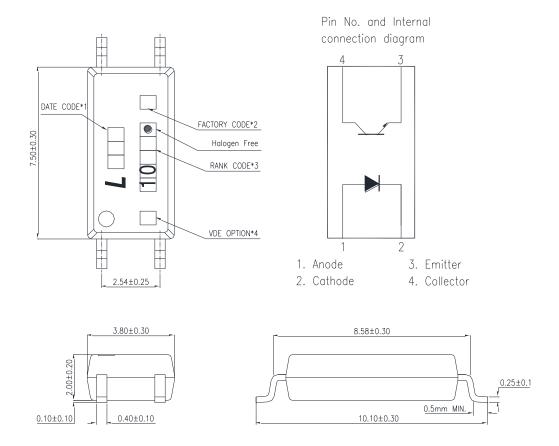
### 1.2 Applications

- Hybrid substrates that require high density mounting.
- Programmable controllers



### 2. PACKAGE DIMENSIONS

### 2.1 LTV-10XX-G series



### Notes:

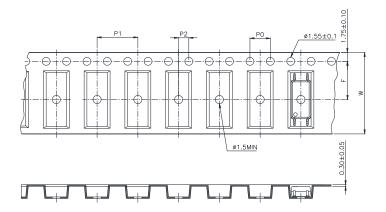
- 1. 1-digit year code and 2-digit work week code
- 2. Factory identification mark shall be marked. (W: China-CZ, X: China-TJ)
- 3. CTR rank.
- 4. "4" or "V" for VDE option.

<sup>\*</sup>All dimensions in millimeters.

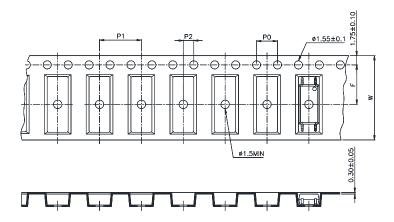


### 3. TAPING DIMENSIONS

### 3.1 LTV-10XX-TP



### 3.2 LTV-10XX-TP1



Description	Symbol	Dimension in mm (inch)
Tape wide	W	16±0.3 (0.47)
Pitch of sprocket holes	P <sub>0</sub>	4±0.1 (0.15)
Distance of compartment	F	7.5±0.1 (0.217)
Distance of compartment	$P_2$	2±0.1 (0.079)
Distance of compartment to compartment	P <sub>1</sub>	8±0.1 (0.315)



### 4. RATING AND CHARACTERISTICS

### 4.1 Absolute Maximum Ratings at Ta=25°C

	Parameter	Symbol	Rating	Unit
	Forward Current	I <sub>F</sub>	60	mA
	Forward Surge Current (t <sub>P.</sub> ≦10µs)	I <sub>FSM</sub>	1.5	А
	Reverse Voltage	$V_R$	6	V
Input	Power Dissipation	Р	100	mW
	Junction Temperature	ΤJ	125	°C
	Thermal Resistance Junction to Ambient	Rth <sub>J-A</sub>	250	°C/W
	Thermal Resistance Junction to Case	Rth <sub>J-C</sub>	180	°C/W
	Collector - Emitter Voltage	$V_{\sf CEO}$	70	V
	Emitter - Collector Voltage	V <sub>ECO</sub>	7	V
Output	Collector Current	Ic	50	mA
	Collector Power Dissipation	Pc	150	mW
	Junction Temperature	ΤJ	125	°C
	Total Power Dissipation	P <sub>tot</sub>	250	mW
1.	Isolation Voltage	V <sub>iso</sub>	5000	$V_{rms}$
	Operating Temperature	$T_{opr}$	-55 ~ +110	°C
	Storage Temperature	T <sub>stg</sub>	-55 ~ +150	°C
2.	Soldering Temperature	T <sub>sol</sub>	260	°C

### 1. AC For 1 Minute, R.H. = $40 \sim 60\%$

Isolation voltage shall be measured using the following method.

- (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.
- (2) The isolation voltage tester with zero-cross circuit shall be used.
- (3) The waveform of applied voltage shall be a sine wave.

### 2. For 10 Seconds



### 4.2 ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C

	Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
	Forward Voltage	V <sub>F</sub>	_	1.25	1.6	V	I <sub>F</sub> =50mA
Input	Reverse Current	I <sub>R</sub>	_	_	10	μΑ	V <sub>R</sub> =4V
	Terminal Capacitance	Ct	_	50	_	pF	V=0, f=1MHz
	Collector Dark Current	I <sub>CEO</sub>	_	10	100	nA	V <sub>CE</sub> =20V, I <sub>F</sub> =0
Output	Collector- Emitter Breakdown Voltage	BV <sub>CEO</sub>	70	_	_	V	I <sub>C</sub> =1mA, I <sub>F</sub> =0
	Emitter-Collector Breakdown Voltage	BV <sub>ECO</sub>	7	_	_	V	I <sub>E</sub> =100μΑ, I <sub>F</sub> =0
TRANSFER CHARACTERISTICS	Current Transfer Ratio	CTR	50	_	600	%	I <sub>F</sub> =5mA V <sub>CE</sub> =5V
	Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	_	_	0.3	V	I <sub>F</sub> =10mA I <sub>C</sub> =1mA
	Isolation Resistance	R <sub>iso</sub>	10 <sup>12</sup>	_	_	Ω	DC500V, 40 ~ 60% R.H.
	Floating Capacitance	Cf	_	0.3	—	pF	V=0, f=1MHz
	Response Time (Rise)	tr	_	3	18	μs	V <sub>CC</sub> =5V,
	Response Time (Fall)	tf	_	4.7	18	μs	$I_C$ =2mA $R_L$ =100 $\Omega$ ,

1. CTR = 
$$\frac{I_C}{I_F} \times 100\%$$

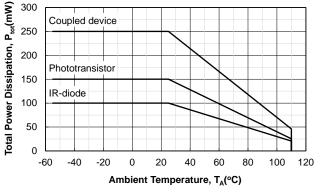


## 5. RANK TABLE OF CURRENT TRANSFER RATIO CTR

CTR Rank	Min.	Тур.	Max.	Unit	Condition	
LTV-1000	50	_	600		_	
LTV-1001	100	_	160			
LTV-1004	100	_	200			
LTV-1005	50	_	150			
LTV-1006	100	_	300	%	% $I_F=5mA, V_{CE}=$	I <sub>F</sub> =5mA, V <sub>CE</sub> =5V, Ta=25°C
LTV-1007	80	_	160			
LTV-1008	130	_	260			
LTV-1009	200	_	400		1	
LTV-1019	250	_	500			
LTV-1002	22	_	_	- % I <sub>F</sub> =1m/		
LTV-1003	34	_	_		1 1m4 \/ 5\/ To 25°C	
LTV-1014	56	_	_		I <sub>F</sub> =1mA, V <sub>CE</sub> =5V, Ta=25°C	
LTV-1018	100	_	200			
LTV-1002	63	_	125	% I <sub>F</sub> =10mA, V <sub>CI</sub>		
LTV-1003	100	_	200		I <sub>F</sub> =10mA, V <sub>CE</sub> =5V, Ta=25°C	
LTV-1014	160	_	320			



### 6. CHARACTERISTICS CURVES



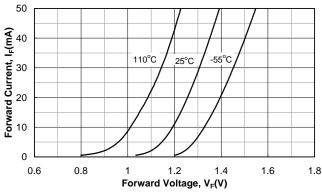
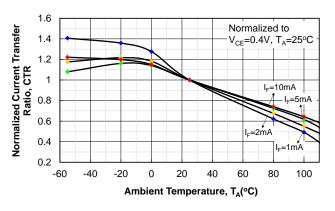


Figure 1. Ptot vs. TA

Figure 4. I<sub>F</sub> vs. V<sub>F</sub>



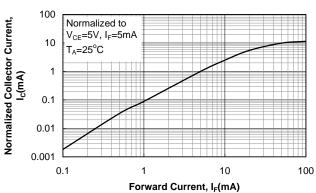
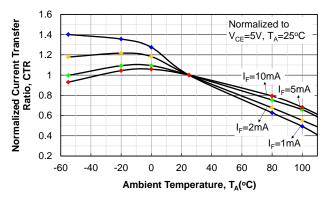


Figure 2. Saturated Normalized CTR vs. T<sub>A</sub>

Figure 5. Normalized I<sub>C</sub> vs. I<sub>F</sub>



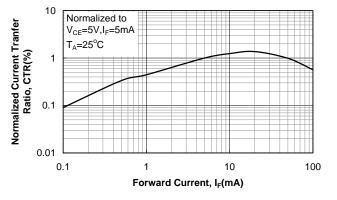
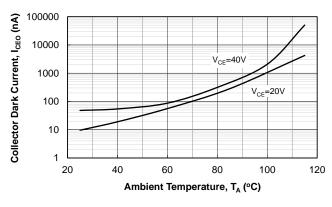


Figure 3. Non-saturated Normalized CTR vs. T<sub>A</sub>

Figure 6. Normalized CTR vs. I<sub>F</sub>





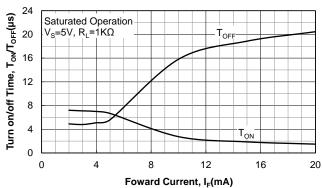
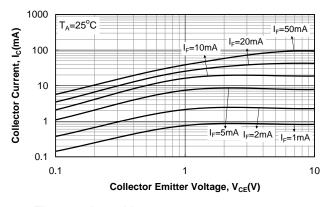


Figure 7. I<sub>CEO</sub> vs. T<sub>A</sub>

Figure 10.  $T_{ON} / T_{OFF} vs. I_F$ 



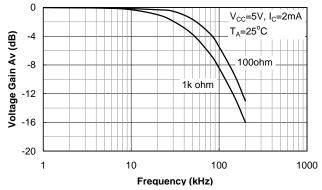


Figure 8. I<sub>C</sub> vs. V<sub>CE</sub>

Figure 11. Frequency Response

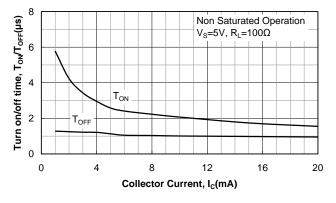


Figure 9.  $T_{ON}$  /  $T_{OFF}$  vs.  $I_{C}$ 

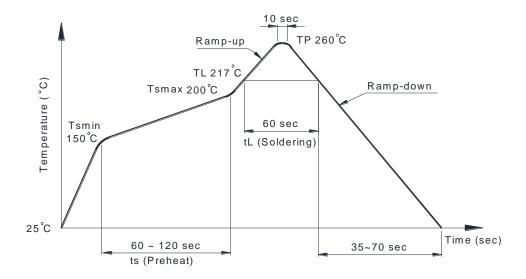


### 7. TEMPERATURE PROFILE OF SOLDERING

### 7.1 IR Reflow soldering (JEDEC-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

Profile item	Conditions		
Preheat			
- Temperature Min (T <sub>Smin</sub> )	150°C		
- Temperature Max (T <sub>Smax</sub> )	200°C		
- Time (min to max) (ts)	90±30 sec		
Soldering zone			
- Temperature (T <sub>L</sub> )	217°C		
- Time (t <sub>L</sub> )	60 sec		
Peak Temperature (T <sub>P</sub> )	260°C		
Ramp-up rate	3°C / sec max.		
Ramp-down rate	3~6°C / sec		





### 7.2 Wave soldering (JEDEC22A111 compliant)

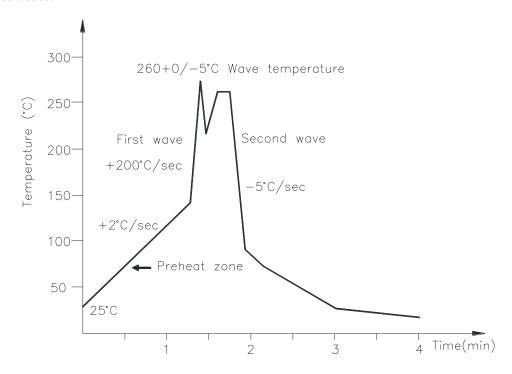
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C

Time: 10 sec.

Preheat temperature:25 to 140°C

Preheat time: 30 to 80 sec.



### 7.3 Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

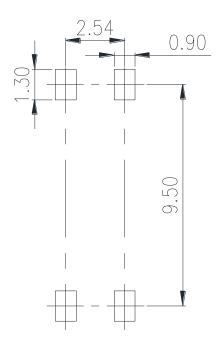
Temperature: 380+0/-5°C

Time: 3 sec max.



## 8. RRECOMMENDED FOOT PRINT PATTERNS (MOUNT PAD)

Unit: mm



### 9. Notes:

- LiteOn is continually improving the quality, reliability, function or design and LiteOn reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
- When requiring a device for any "specific" application, please contact our sales in advice.
- If there are any questions about the contents of this publication, please contact us at your convenience.
- The contents described herein are subject to change without prior notice.
- Immerge unit's body in solder paste is not recommended.